

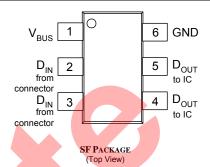
PRODUCTION DATA SHEET

ABSOLUTE MAXIMUM RATINGS

Steady State Power	100mW
ESD Air Discharge per IEC61000-4-2	16KV
ESD Contact Discharge per IEC61000-4-2	10KV
Lead Soldering Temperature (10 Seconds)	260°C
Operating Temperature	40°C to +125°C
Storage Temperature Range	55°C to +150°C

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

PACKAGE PIN OUT



THERMAL DATA

\mathbf{SF}	Plastic SOT-23	6-Pin
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THERMAL RESISTANCE-JUNCTION TO CASE, θ_{JC}	62 °C/W
THERMAL RESISTANCE-JUNCTION TO AMBIENT, θ_{JA}	96 °C/W

Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

The θ_{JA} numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

•	FUNCTIONAL PIN DESCRIPTION				
	Name	Description			
	VBUS	Bus Voltage			
	DIN	Data In			
	GND	Ground			
	DOUT	Data Out			

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, the following specifications apply over the operating ambient temperature -40°C $\leq T_A \leq$ +125°C except where otherwise noted.

Parameter	Symbol	Test Conditions		LX7202-xx		Units
r al allietei	Symbol			Тур	Max	Ullits
Stand-Off Voltage	VR_{WM}				5.25	V
Breakdown Voltage	V_{BR}	IR = 1mA	6			V
Leakage Current	I_R	VRWM = 5.25V, T = 25°C			1	μA
Series Resistance (-15)	R_{S}	Each Line	13.5	15	16.5	Ω
Series Resistance (-22)	Rs	Each Line	19.8	22	24.2	Ω
Temperature Coefficient of R _S	T _{COEFF}	Each Line		200		ppm
Pull Up Resistance	R _{PU}	Each Line	1.35	1.5	1.65	ΚΩ
Capacitor	С	Each Line		47		pF
Total Capacitance	C _{TOT}	Between I/O Pins and Ground, Each Device VR = 0V, f = 1MHz	54	60	66	pF

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APPLICATION CIRCUITS

Host or Hub (downstream) port Peripheral (upstream) port LX7201 USB Transceiver Transceiver Transceiver Transceiver Transceiver

Figure 1 - Typical Application

APPLICATION INFORMATION

The LX7202 meets the requirements of the USB v1.1 and USB 2.0 Full Speed specification for device termination, EMI filtering and ESD protection. The RS resistor provides the proper signal termination; the 47pF capacitor controls the signal rise and fall slew; the TVS diodes protect the IC from ESD damage; and the total capacitance and resistance creates a low pass filter eliminating the high frequency energy from the circuit. The LX7202 can configure the upstream port for either Full-Speed or Low-Speed operation. The figures below show the proper connection in accordance with the USB specification.

FULL SPEED DEVICE

The USB 2.0 specification offers a 12 Mbps data transfer rate known as Full-Speed which requires a 1.5 k Ω pull-up resistor to be connected to the D+ line. Slew rate control is accomplished with 47pF attached to the transceiver before the $R_{\rm S}$.

- Voltage Supply (Vbus) is connected to Pin 1
- Ground is connected to Pin 6
- D+ from the connector is routed to Pin 3 (1.5 kΩ pull-up resistor) and Pin 4 to the D+ line of the USB Transceiver
- D- from the connector is routed to Pin 2 and Pin 5 to the D- line of the USB Transceiver

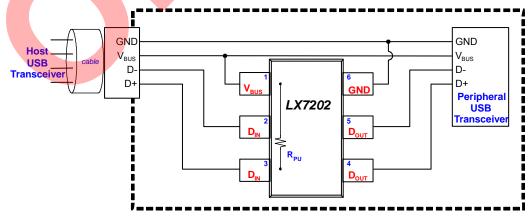


Figure 2 – Connection for Full Speed Operation



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APPLICATION INFORMATION (CONTINUED)

LOW SPEED DEVICE

The USB v1.1 specification offers a 1.5 Mbps data transfer rate known as Low-Speed which requires a 1.5 k Ω pull-up resistor to be connected to the D- line. Slew rate control is accomplished with 47pF attached to the transceiver before the $R_{\rm S}$.

- Voltage Supply (Vbus) is connected to Pin 1
- Ground is connected to Pin 6
- D+ from the connector is routed to Pin 2 and Pin 5 to the D+ line of the USB Transceiver
- D- from the connector is routed to Pin 3 (1.5 $\rm k\Omega$ pull-up resistor) and Pin 4 to the D- line of the USB Transceiver

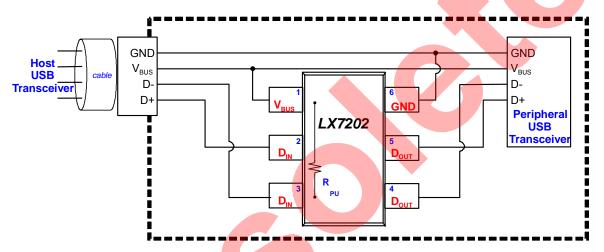


Figure 3 - Connection for Low Speed Operation

ELECTROMAGNETIC EMISSION AND SUSCEPTABILITY

emission and susceptibility. There are two types of emissions of 0.45 to 30 MHz and Radiated emissions with frequency of emission of 30 MHz to 40 GHz. All digital computing devices including the peripheral devices must comply. Examples of peripheral devices include terminals, printers, external floppy disk drives and other fixed adjustable data storage devices, video monitors, keyboards,

control cards, interface boards, external memory expansion cards and other input/output devices that may or may not contain digital circuitry. LX7202 is optimized to minimize the radiated EMI which is the primary concern in devices using USB. Refer to the typical filter response curve for the attenuation characteristics of LX7202 over the frequency range of 30KHz to 6GHz.



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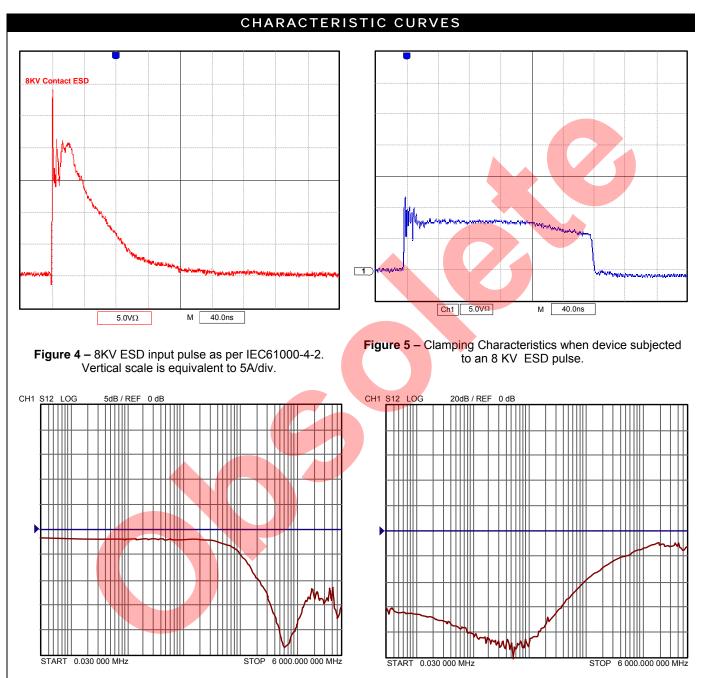


Figure 6 – Frequency response curve. Low insertion loss in the pass band and -20dB attenuation at 800-900 MHz. Better than -10dB attenuation at the WLAN frequencies of 2.4 and 5.0-6.0 GHz.

Figure 7 – Analog Crosstalk between the two datalines D-and D+

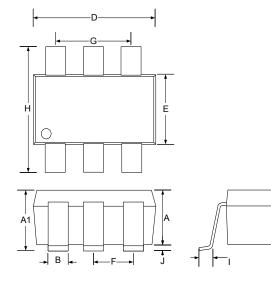


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PACKAGE DIMENSIONS

SE

6 Pin Plastic SOT-23

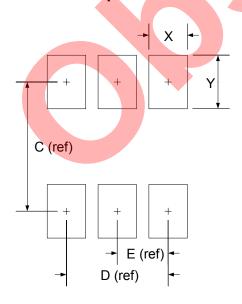


	MILLIMETERS		INC	INCHES	
Dim	MIN	MAX	MIN	MAX	
Α	0.90	1.30	0.035	0.051	
A1	0.90	1.45	0.035	0 .057	
В	0.25	0.50	0.010	<mark>0</mark> .020	
С	0.09	0.20	0.004	0.008	
D	2.80	3.10	0.110	0.122	
E	1.50	1.75	0.059	0.069	
F	0.95 BSC 1.90 BSC		0.038 BSC 0.075 BSC		
G					
H	2.60	3.00	0.102	0.118	
	0.35	0.55	0.014	0.022	
J	0.00	0.15	0.000	0.006	
K	10° MAX		10° MAX		

Note:

 Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.

Recommended Footprint



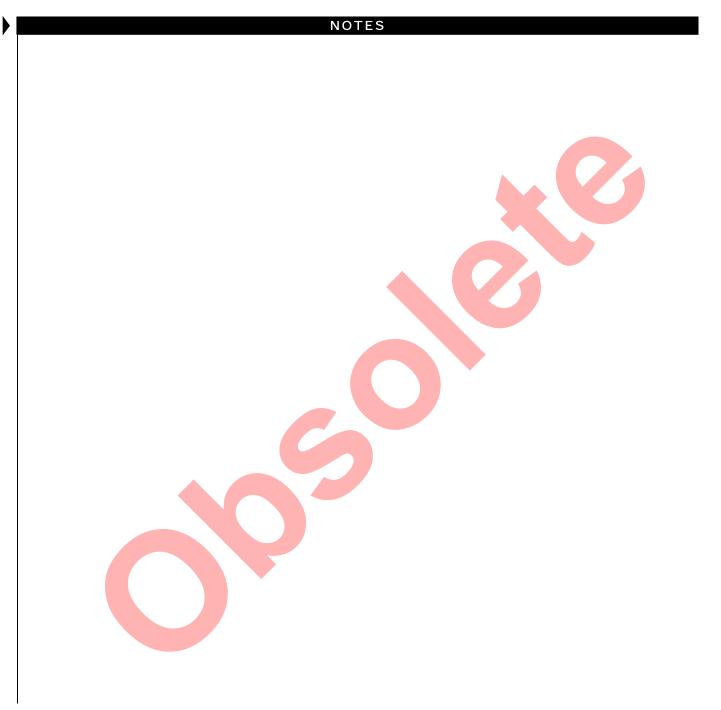
	MILLIN	METERS	INCHES	
Dim	MIN	MAX	MIN	MAX
С	-	2.40	-	0.094
D	-	1.90	-	0.074
E	-	0.95	-	0.037
Х	-	0.70	-	0.028
Υ	_	1 00	_	0.039



LX7202-xx

EMI Filter & ESD Protection for Up Stream USB Ports

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